

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
a semiconductor chip;
a mold resin sealing the semiconductor chip; and
a plurality of conductor leads extending from an inside of the mold resin to an outside thereof, each having a portion arranged inside the mold resin defining an internal terminal portion and a portion arranged outside the mold resin defining an external terminal portion, and an electrode of the semiconductor chip and the internal terminal portion of the conductor lead being connected;
wherein the internal terminal portion of at least one of the conductor leads ~~forms~~ has an inductance element portion, ~~at least a part of which is~~ with a width narrower than the external terminal portion[.],
the inductance element portion has a meandering planar shape, and
the conductor lead with the inductance element portion has an overlapping portion overlapping a lower surface of the semiconductor chip, the semiconductor chip being mounted on and connected with the conductor lead at the overlapping portion.
2. (Canceled).
3. (Canceled).
4. (Currently Amended) The semiconductor device according to claim [[3]] 1, wherein in the overlapping portion of the electrode of the semiconductor chip and the conductor lead, the connection is made via an electrical conductor in a via hole formed in the semiconductor chip.

5. (Currently Amended) The semiconductor device according to claim [[3]] 1, wherein the overlapping portion of the conductor lead forms a die pad portion on which the semiconductor chip is mounted.
6. (Original) The semiconductor device according to claim 1, wherein the conductor lead having the inductance element portion is connected to a source of a field-effect transistor or an emitter of a bipolar transistor formed in the semiconductor chip.
7. (Original) The semiconductor device according to claim 1, wherein the conductor lead having the inductance element portion is connected to a gate or a drain of a field-effect transistor or a base or a collector of a bipolar transistor formed in the semiconductor chip.
8. (Original) The semiconductor device according to claim 1, wherein at least one of the conductor leads functions as a choke inductor or matching element.
9. (New) A semiconductor device comprising:
 - a semiconductor chip;
 - a mold resin sealing the semiconductor chip; and
 - a plurality of conductor leads extending from an inside of the mold resin to an outside thereof, each having a portion arranged inside the mold resin defining an internal terminal portion and a portion arranged outside the mold resin defining an external terminal portion, and an electrode of the semiconductor chip and the internal terminal portion of the conductor lead being connected;

wherein each of the internal terminal portions of two of the conductor leads having the same shape has an inductance element portion with a width narrower than the external terminal portion, and

the two internal terminal portions are arranged symmetrically with respect to the semiconductor chip, with the semiconductor chip being interposed therebetween.